



Date Created: 2/10/2004
Date Issued: 3/10/2004
PCN # 20040611

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

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PCN Type: Alternate Assembly Site Location/Qualification

Effectivity

Expected 1st Device Shipment Date: 6/10/2004
Earliest Year/Work Week of Changed Product: 0424
(Note: Package marking may differ from this format)

Product ID (Description):

FSD210, FSD200 of 7pin-DIP.
FSD210H, FSDH0165, FSDH0165D, FSDH0165G of 8pin-DIPH

Description of Change:

Fairchild Semiconductor Corporation's manufacturing facility in Penang, Malaysia will be qualified as an alternative assembly and test site for Fairchild's 7-pin DIP and 8-pin DIPH packages. These packages will be qualified for production in Penang with Pb-free plating. This product will also continue to be assembled and tested by the currently qualified supplier, SZEC in China. As previously noted in PCN# 20032701, SZEC will also be converting to Pb-free plating. The current schedule is such that at the time these products are approved for shipment from Penang, there will be no differences in assembly materials, plating or packing materials, except tube dimensions.

	Width (top-side)	Width (bottom-side)	Height	Material thickness	Tube Length
From	9.00mm	12.90mm	11.10mm	0.5mm	500.0mm
To	10.65mm	13.97mm	11.43mm	0.5mm	501.0mm

Effect of Change:

This change will not affect any electrical characteristics & reliability.
The change will enlarge the production capacity to meet customer's needs.
There is no difference in assembly materials or packing materials.
Under Fairchild's control, the same program will be applied to test the products from
the Penang Location

Qualification:

The qualification plan is intended to meet our criteria for qualifying an alternate
assembly & test site, the overall quality and reliability of our products.

Qual/REL Plan Numbers

Additional Qualification Data

* 8DIPH PKG QUAL PLAN

Device : FSD210H

Rel items	Test Conditions	Sample Size	Read Out Time
HTRB	Vdd=560V, Ta=125□	77 ea	168,500,1000HR
HTOL	Vdd=100V, Vcc=17V, Vstr=400V, Ta=125□	77 ea	168,500,1000HR
HTSL	Ta= 150□	77 ea	168,500,1000HR
THBT	85□/ 85%, Vcc= 15V->10V	77 ea	168,500,1000HR
TMCL	-65□ ~ +150□	77 ea	200,500CL
ACLV	Ta=121□, RH=100%, Pressure=15 PSIG	77 ea	96HR

* 7DIP PKG QUAL PLAN

Device : FSD210

Rel items	Test Conditions	Volume	Read Out Time
HTRB	Vdd=560V, Ta=125□	77 ea	168,500,1000HR
HTOL	Vdd=100V, Vcc=17V, Vstr=400V, Ta=125□	77 ea	168,500,1000HR
HTOL (J-FET)	Vstr=560V, Ta=125□	77 ea	168,500,1000HR
HTSL	Ta= 150□	77 ea	168,500,1000HR
THBT	85□/ 85%, Vcc= 15V->10V	77 ea	168,500,1000HR
TMCL	-65□ ~ +150□	77 ea	200,500CL

ACLV	Ta=121□, RH=100%, Pressure=15 PSIG	77 ea	96HR
Dynamic	Vin=220Vac	30 ea	96HR

Affected FSIDs

FSD200
FSDH0165

FSD210
FSDH0165D

FSD210H
FSDH0165G